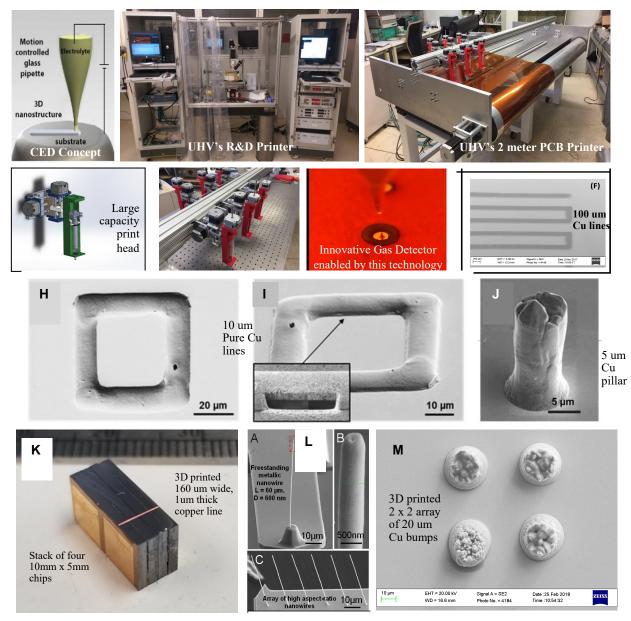
US-DOE SBIR Sponsored R&D Projects

DE-SC0017233: A Scalable Additive Manufacturing Technology for Large Area Printed Circuit Boards **DE-SC0018905:** An Innovative Additive Manufacturing Technology for High Density Interconnects



PI: Nalin Kumar, Ph.D. Project Durations: 2017 to 2020 Funding: Total - \$1,300,000

Project Participants: UHV Technologies, Inc., University of Texas at Dallas and University of Michigan

Patents Pending.